



**THE DATASHEET OF
CZ12010T0050GTR**

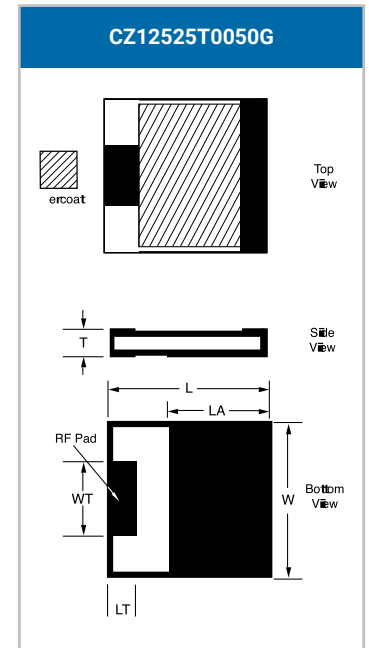
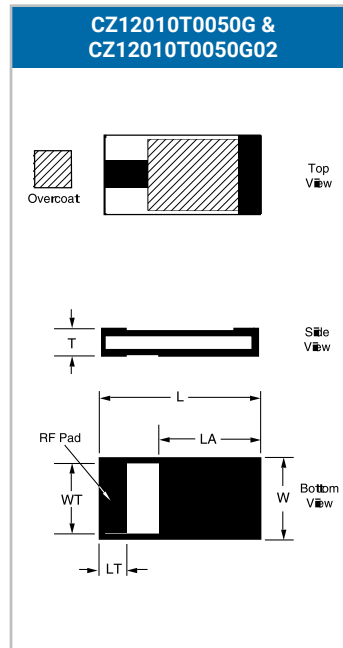


Surface Mount Chip Terminations

CZ1 Style

GENERAL SPECIFICATIONS

- **Nominal Impedance:** 50 Ω
- **Resistive Tolerance:** $\pm 2\%$ standard
- **Operating Temp Range:** -55 to +150°C
- **Temperature Coefficient:** ± 150 ppm/°C
- **Resistive Elements:** Tantalum, Thin Film Processed
- **Substrate Material:** Aluminum Nitride
- **Terminals:** Silver over Nickel
- **Lead-Free, RoHS Compliant**
- **Reliability:** MIL-PRF-55342
- **Tape & Reel Specifications:**

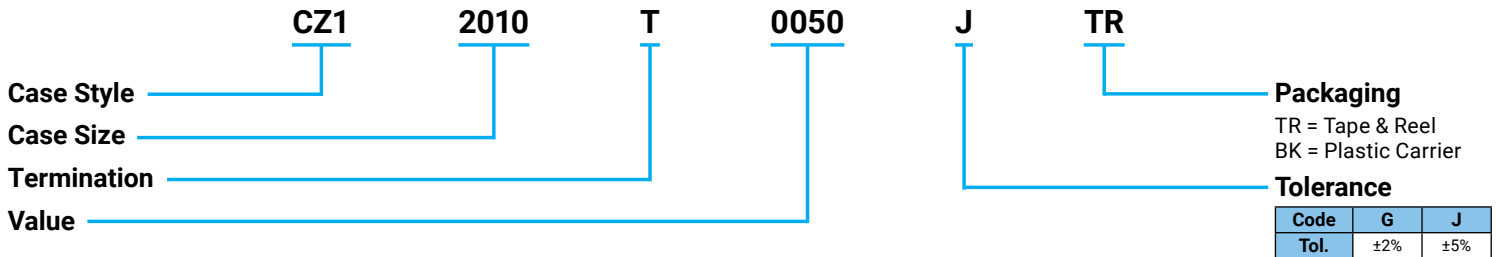


Values in Inches

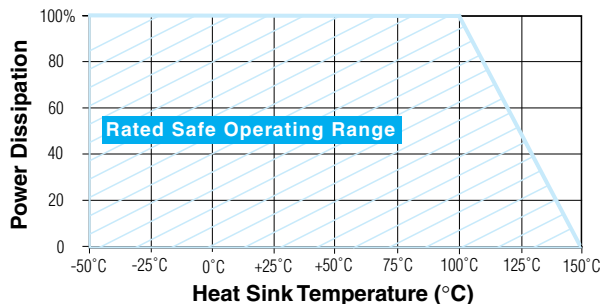
Part Number	W $\pm .010$	L $\pm .010$	T $\pm .005$	LT $\pm .005$	WT $\pm .005$	LA $\pm .005$	Frequency Range (GHz)	VSWR (Typ.)	Power Max* (Watts)
CZ12010T0050G	.100	.200	.040	.040	.090	.115	DC - 3.0	1.20:1	10W
CZ12010T0050G02	.100	.200	.040	.020	.090	.140	DC - 3.0	1.20:1	10W
CZ12525T0050G	.245	.245	.040	.030	.125	.170	DC - 4.0	1.25:1	20W

* Test Condition: Chip soldered to a via patch on a 30-mil-thick Rogers R04350 board; Land surfaces at 100° C; maximum rated power applied.
 Specification: The resistance of the film shall change no more than 0.5% during and after a 1000-hr. Burn-in per Mil-PRF-55342.

HOW TO ORDER



POWER DERATING

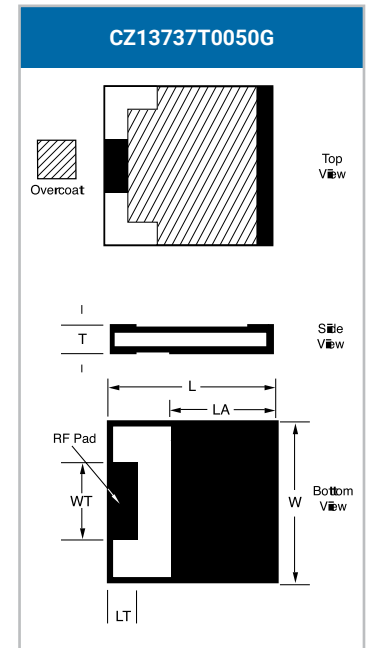
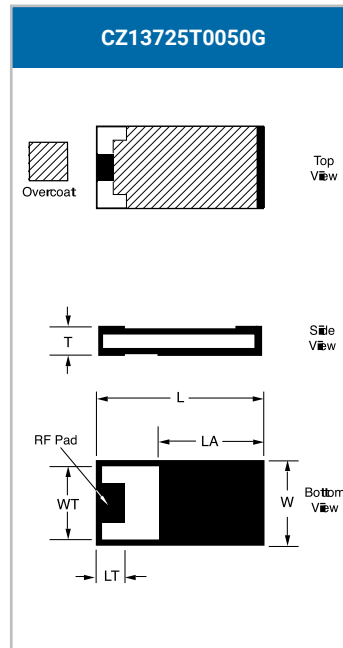


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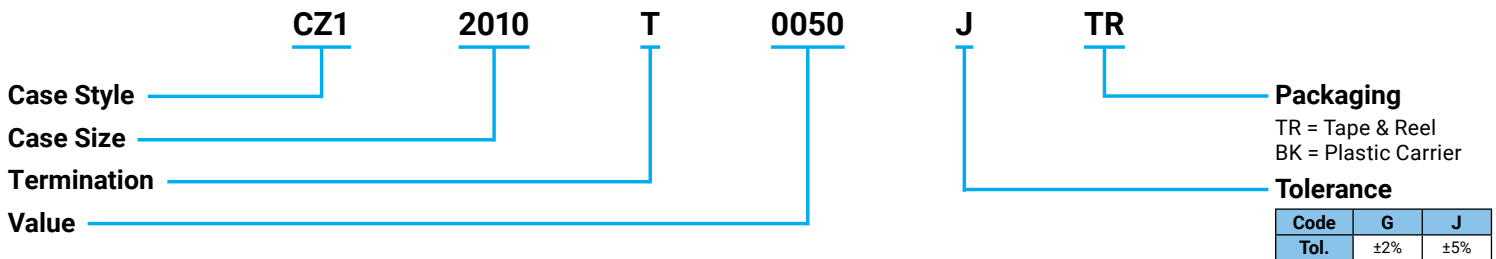


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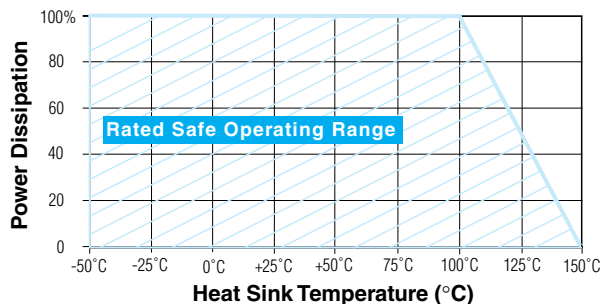
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CZ13725T0050G	.250	.375	.040	.050	.125	.260	DC - 2.2	1.20:1	30W
CZ13737T0050G	.370	.370	.040	.050	.125	.275	DC - 3.0	1.25:1	40W

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HOW TO ORDER





POWER DERATING



Looking for pricing, stock, or lifecycle information?

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-  [American Technical Ceramics](#) Information

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-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
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